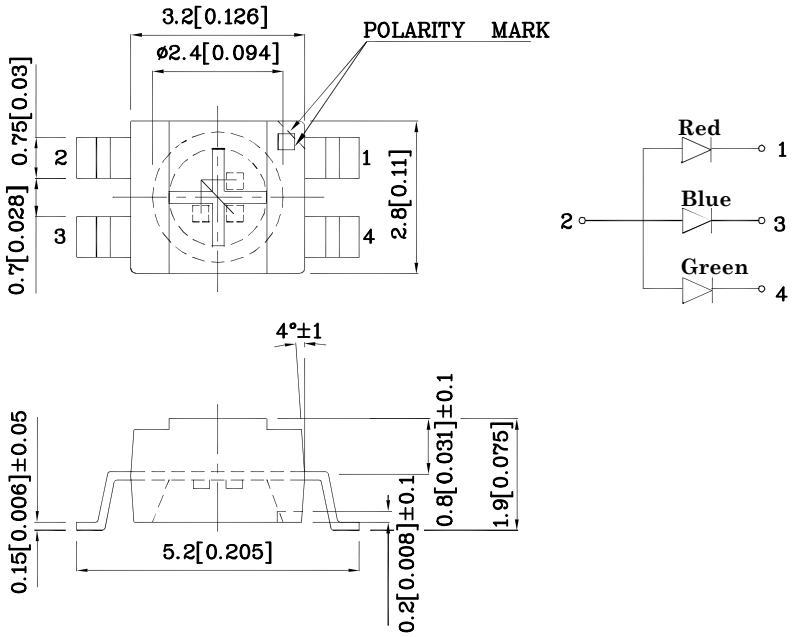
Features

- Ideal for indication light on hand held products
- Long life and robust package
- Standard Package: 2000pcs/ Reel
- MSL (Moisture Sensitivity Level): 3
- RoHS compliant.

ATTENTION
OBSERVE PRECAUTIONS
FOR HANDLING
ELECTROSTATIC
DISCHARGE
SENSITIVE
DEVICES

Package Schematics



Notes:
1. All dimensions are in millimeters (inches).
2. Tolerance is ±0.2(0.008") unless otherwise noted.
3. Specifications are subject to change without notice.

Absolute Maximum Ratings (T_A=25°C)		**Red (AlGaInP)**	**Blue (InGaN)**	**Green (InGaN)**	**Unit**
Reverse Voltage	V_R	5	5	5	V
Forward Current	I_F	30	30	30	mA
Forward Current (Peak) 1/10 Duty Cycle 0.1ms Pulse Width	i_{FS}	185	150	150	mA
Power Dissipation	P_D	75	120	123	mW
Electrostatic Discharge Threshold (HBM)		3000	250	450	V
Operating Temperature	T_A	-40 ~ +85			°C
Storage Temperature	Tstg				

A Relative Humidity between 40% and 60% is recommended in ESD-protected work areas to reduce static build up during assembly process (Reference JEDEC/JESD625-A and JEDEC/J-STD-033)

Operating Characteristics (T_A=25°C)		**Red (AlGaInP)**	**Blue (InGaN)**	**Green (InGaN)**	**Unit**
Forward Voltage (Typ.) (I_F=20mA)	V_F	1.95	3.3	3.3	V
Forward Voltage (Max.) (I_F=20mA)	V_F	2.5	4	4.1	V
Reverse Current (Max.) (V_R=5V)	I_R	10	50	50	uA
Wavelength of Peak Emission CIE127-2007* (Typ.) (I_F=20mA)	λP	645*	460*	515*	nm
Wavelength of Dominant Emission CIE127-2007* (Typ.) (I_F=20mA)	λD	630*	465*	525*	nm
Spectral Line Full Width At Half-Maximum (Typ.) (I_F=20mA)	△λ	28	25	35	nm
Capacitance (Typ.) (V_F=0V, f=1MHz)	C	35	100	45	pF

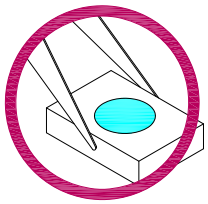
Part Number	Emitting Color	Emitting Material	Lens-color	Luminous Intensity CIE127-2007* (I_F=20mA) mcd min.	Luminous Intensity CIE127-2007* (I_F=20mA) mcd typ.	Wavelength CIE127-2007* λP nm	Viewing Angle 2θ 1/2
XZMDKCBDDG45S-9	Red	AlGaInP	Water Clear	55*	108*	645*	120°
	Blue	InGaN		55*	98*	460*	
	Green	InGaN		400*	497*	515*	

*Luminous intensity value and wavelength are in accordance with CIE127-2007 standards.

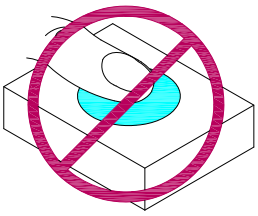
Handling Precautions

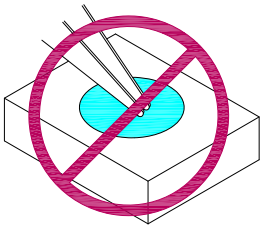
Compare to epoxy encapsulant that is hard and brittle, silicone is softer and flexible. Although its characteristic significantly reduces thermal stress, it is more susceptible to damage by external mechanical force.
As a result, special handling precautions need to be observed during assembly using silicone encapsulated LED products. Failure to comply might lead to damage and premature failure of the LED.

1. Handle the component along the side surfaces by using forceps or appropriate tools.

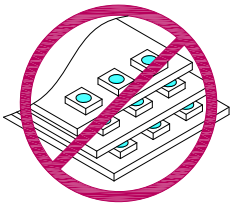


2. Do not directly touch or handle the silicone lens surface. It may damage the internal circuitry.

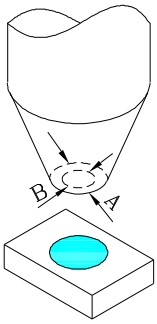




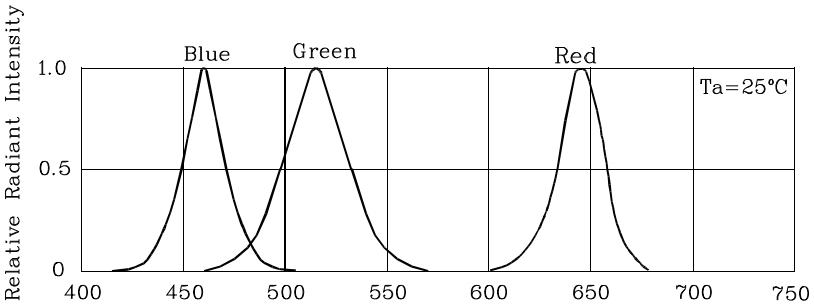
3. Do not stack together assembled PCBs containing exposed LEDs. Impact may scratch the silicone lens or damage the internal circuitry.



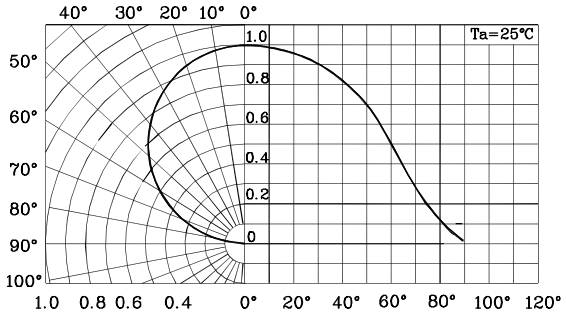
4.1. The inner diameter of the SMD pickup nozzle should not exceed the size of the LED to prevent air leaks.
4.2. A pliable material is suggested for the nozzle tip to avoid scratching or damaging the LED surface during pickup.
4.3. The dimensions of the component must be accurately programmed in the pick-and-place machine to insure precise pickup and avoid damage during production.



5. As silicone encapsulation is permeable to gases, some corrosive substances such as H_2S might corrode silver plating of lead-frame. Special care should be taken if an LED with silicone encapsulation is to be used near such substances.

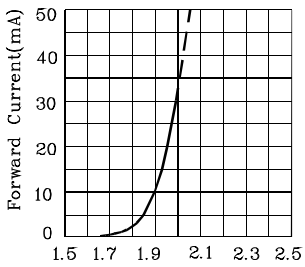


RELATIVE INTENSITY Vs. CIE WAVELENGTH

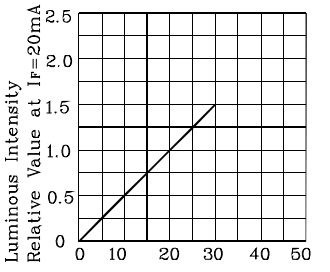


SPATIAL DISTRIBUTION

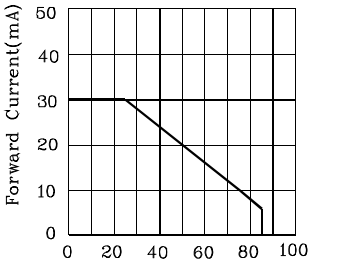
❖ Red



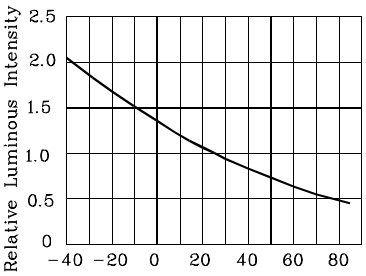
FORWARD CURRENT Vs.
FORWARD VOLTAGE



LUMINOUS INTENSITY Vs.
FORWARD CURRENT

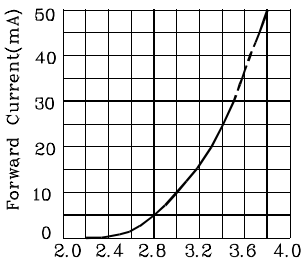


FORWARD CURRENT
DERATING CURVE

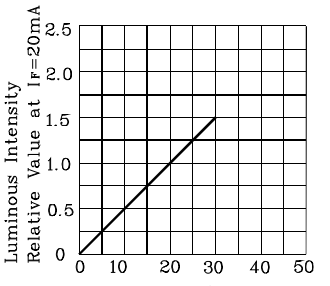


LUMINOUS INTENSITY Vs.
AMBIENT TEMPERATURE

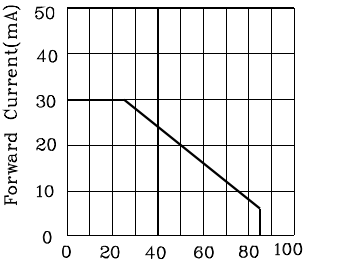
❖ Blue



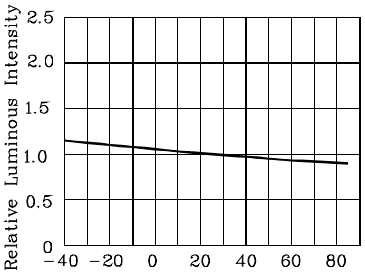
FORWARD CURRENT Vs.
FORWARD VOLTAGE



LUMINOUS INTENSITY Vs.
FORWARD CURRENT

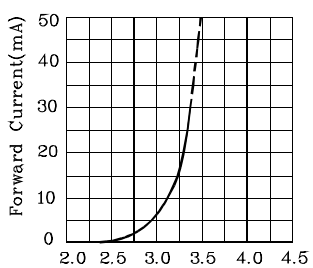


FORWARD CURRENT
DERATING CURVE

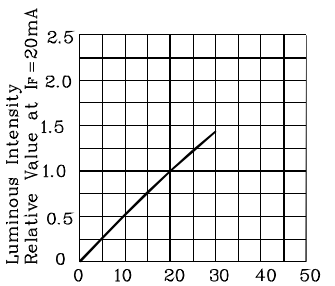


LUMINOUS INTENSITY Vs.
AMBIENT TEMPERATURE

❖ Green

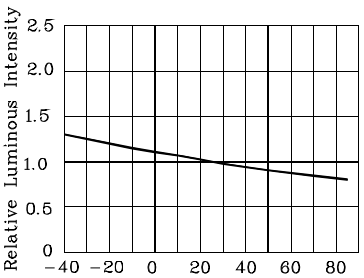


FORWARD CURRENT Vs
FORWARD VOLTAGE



LUMINOUS INTENSITY Vs.
FORWARD CURRENT

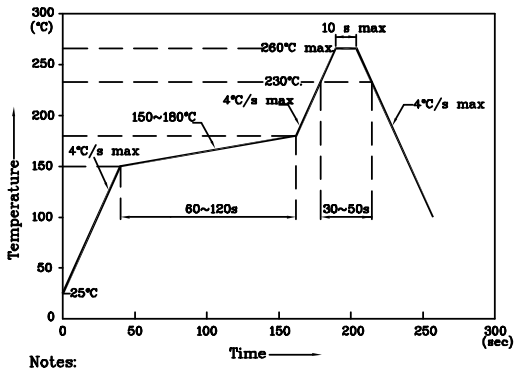
FORWARD CURRENT
DERATING CURVE



LUMINOUS INTENSITY Vs.
AMBIENT TEMPERATURE

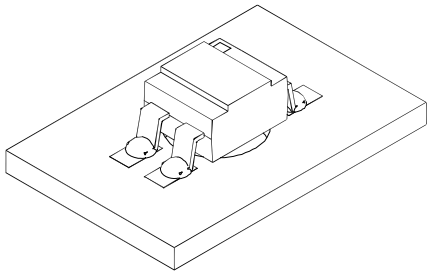
LED is recommended for reflow soldering and soldering profile is shown below.

Reflow Soldering Profile for SMD Products (Pb−Free Components)

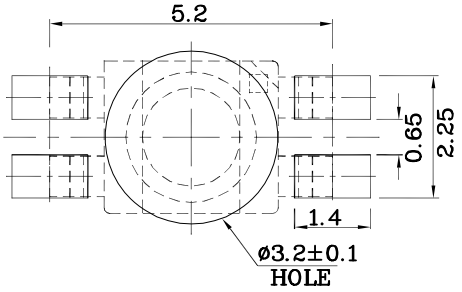


Notes:
1. Maximum soldering temperature should not exceed 260°C
2. Recommended reflow temperature: 145°C−260°C
3. Do not put stress to the epoxy resin during high temperatures conditions

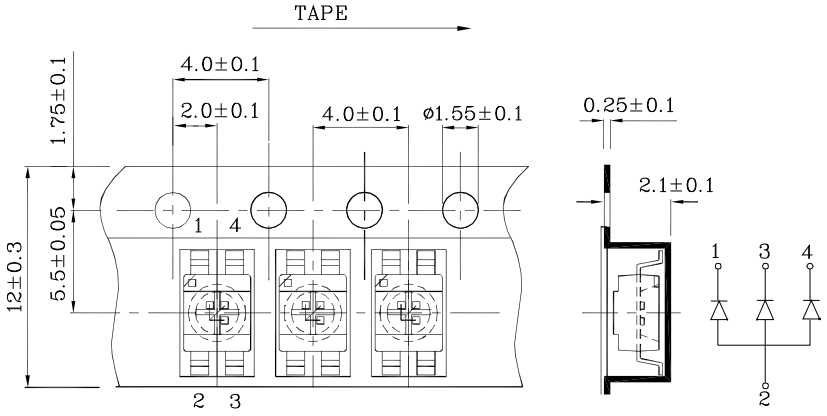
❖ **The device has a single mounting surface. The device must be mounted according to the specifications.**



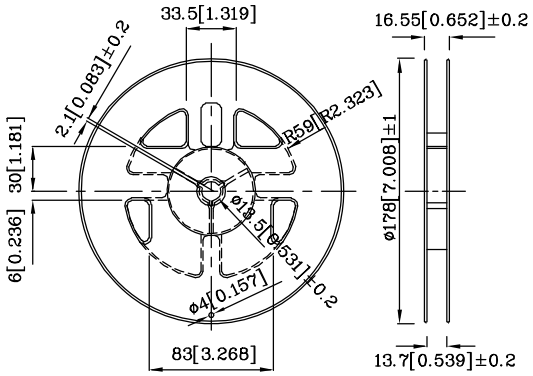
❖ **Recommended Soldering Pattern (Units : mm; Tolerance: ± 0.1)**



❖ **Tape Specification (Units : mm)**



❖ **Reel Dimension**



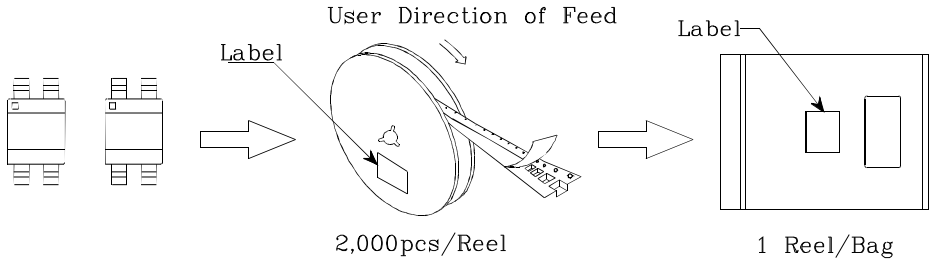
Remarks:

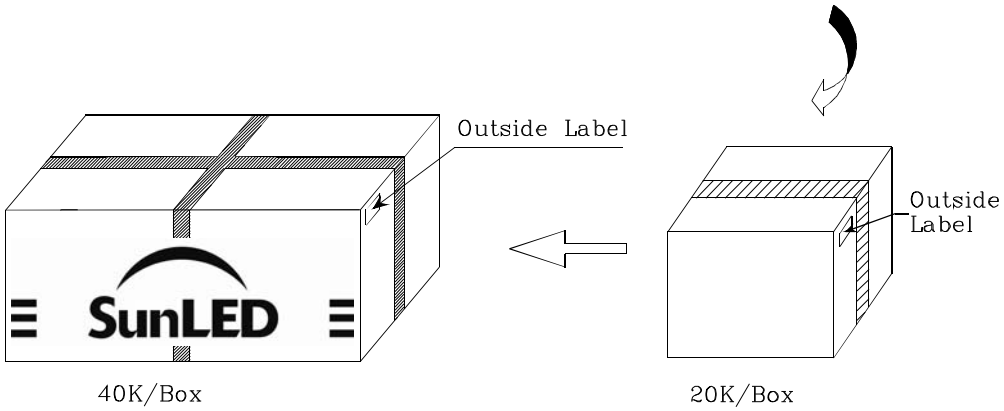
If special sorting is required (e.g. binning based on forward voltage, Luminous intensity / luminous flux, or wavelength), the typical accuracy of the sorting process is as follows:

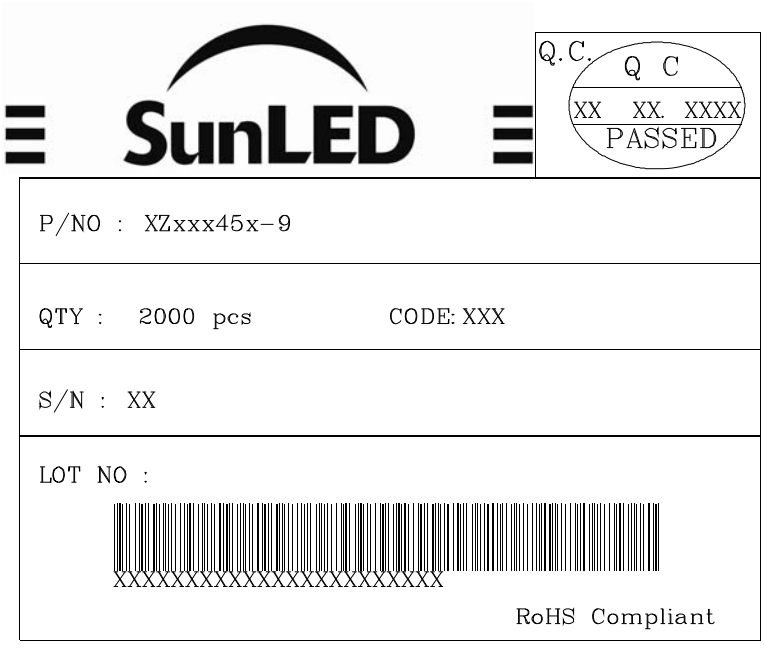
1. Wavelength: +/-1nm
2. Luminous intensity / luminous flux: +/-15%
3. Forward Voltage: +/-0.1V

Note: Accuracy may depend on the sorting parameters.

PACKING & LABEL SPECIFICATIONS







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